

# HEXFRED® Ultrafast Soft Recovery Diode, 70 A



PRIMARY CHARACTERISTICS					
V <sub>R</sub>	1200 V				
V <sub>F</sub> (typical)	2.2 V				
t <sub>rr</sub> (typical)	48 ns				
I <sub>F(DC)</sub> at T <sub>C</sub> , per module	70 A at 121 °C				
Package	SOT-227				

#### **FEATURES**

- · Fast recovery time characteristic
- Electrically isolated base plate
- Antiparallel diodes
- Large creepage distance between terminal
- · Simplified mechanical designs, rapid assembly
- · Designed and qualified for industrial level
- UL approved file E78996





#### **DESCRIPTION / APPLICATIONS**

This SOT-227 modules with HEXFRED® rectifier are in antiparallel configuration. The antiparallel configuration is used for simple series rectifier and high voltage application. The semiconductor in the SOT-227 package is isolated from the copper base plate, allowing for common heatsinks and compact assemblies to be built.

These modules are intended for general applications such as HV power supplies, electronic welders, motor control and inverters.

ABSOLUTE MAXIMUM RATINGS					
PARAMETER	SYMBOL	TEST CONDITIONS	MAX.	UNITS	
Cathode to anode voltage	V <sub>R</sub>		1200	V	
Continuous forward current, per leg	I <sub>F</sub>	T <sub>C</sub> = 121 °C	35	Λ	
Single pulse forward current	I <sub>FSM</sub>	T <sub>J</sub> = 25 °C	350	Α	
Maying an action discinction and los	-	T <sub>C</sub> = 25 °C	357	W	
Maximum power dissipation, per leg	P <sub>D</sub>	T <sub>C</sub> = 100 °C	143		
RMS isolation voltage	V <sub>ISOL</sub>	Any terminal to case, t = 1 minute	2500	V	
Operating junction and storage temperature range	T <sub>J</sub> , T <sub>Stg</sub>		-55 to +150	°C	

<b>ELECTRICAL SPECIFICATIONS</b> (T <sub>J</sub> = 25 °C unless otherwise specified)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Cathode to anode breakdown voltage	$V_{BR}$	I <sub>R</sub> = 100 μA	1200	-	-	
		I <sub>F</sub> = 30 A	-	2.2	3.0	V
Forward voltage, per leg	V <sub>FM</sub>	I <sub>F</sub> = 60 A	-	2.8	4.0	
		I <sub>F</sub> = 30 A, T <sub>J</sub> = 125 °C	-	2.13	-	
		I <sub>F</sub> = 60 A, T <sub>J</sub> = 125 °C	-	2.70	-	
		I <sub>F</sub> = 30 A, T <sub>J</sub> = 150 °C	-	2.04	-	
		I <sub>F</sub> = 60 A, T <sub>J</sub> = 150 °C	-	2.65	-	
Reverse leakage current, per leg	I <sub>RM</sub>	$V_R = V_R$ rated	-	2.0	75	μΑ
		$T_J = 125  ^{\circ}\text{C},  V_R = V_R  \text{rated}$	-	1.6	5	mΛ
		$T_J = 150  ^{\circ}\text{C},  V_R = V_R  \text{rated}$	-	5	10	mA



<b>DYNAMIC RECOVERY CHARACTERISTICS</b> (T <sub>J</sub> = 25 °C unless otherwise specified)							
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNITS
		$I_F = 1 A$ ; $dI_F/d$	$It = 200 \text{ A/}\mu\text{s}; V_R = 30 \text{ V}$	-	48	ı	ns
Reverse recovery time, per leg	t <sub>rr</sub>	T <sub>J</sub> = 25 °C	$I_F = 50 \text{ A}$ $dI_F/dt = -200 \text{ A/}\mu\text{s}$ $V_R = 200 \text{ V}$	-	145	-	
		T <sub>J</sub> = 125 °C		-	218	-	
Dook receivery ourrent per les		T <sub>J</sub> = 25 °C		-	13	-	Α
Peak recovery current, per leg	I <sub>RRM</sub>	T <sub>J</sub> = 125 °C		-	19	-	
Reverse recovery charge, per leg	Q <sub>rr</sub>	T <sub>J</sub> = 25 °C		-	910	-	nC
		T <sub>J</sub> = 125 °C		-	1920	=	IIC
Junction capacitance, per leg	C <sub>T</sub>	V <sub>R</sub> = 1200 V		-	27	-	pF

THERMAL - MECHANICAL SPECIFICATIONS						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Junction to case, single leg conducting	В		-	-	0.35	
Junction to case, both legs conducting	$R_{thJC}$		-	-	0.175	°C/W
Case to heatsink	R <sub>thCS</sub>	Flat, greased surface	-	0.05	-	
Weight			-	30	-	g
Mounting toyage		Torque to terminal	-	-	1.1 (9.7)	Nm (lbf.in)
Mounting torque		Torque to heatsink	-	-	1.8 (15.9)	Nm (lbf.in)
Case style				S	OT-227	•

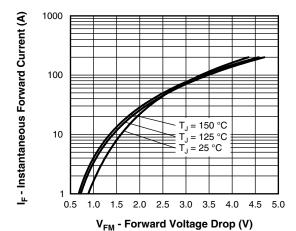


Fig. 1 - Typical Forward Voltage Drop Characteristics

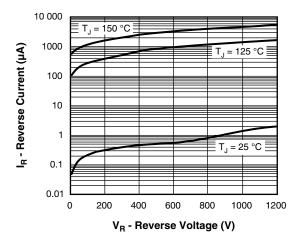
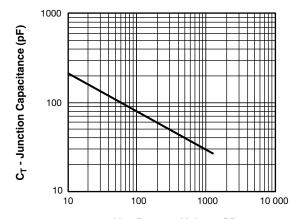


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage



V<sub>R</sub> - Reverse Voltage (V)
Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

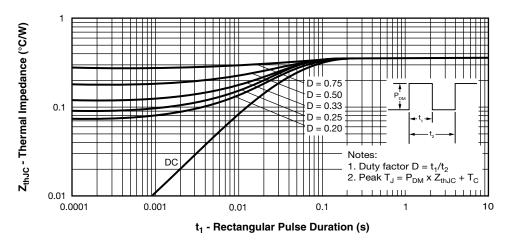


Fig. 4 - Maximum Thermal Impedance Z<sub>thJC</sub> Characteristics

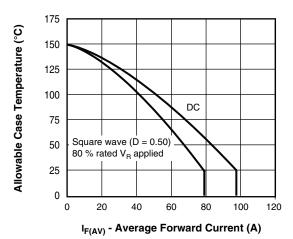


Fig. 5 - Maximum Allowable Case Temperature vs. Average Forward Current

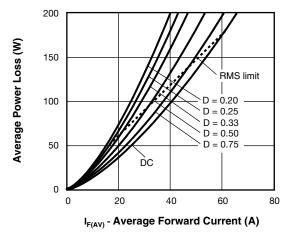


Fig. 6 - Forward Power Loss Characteristics

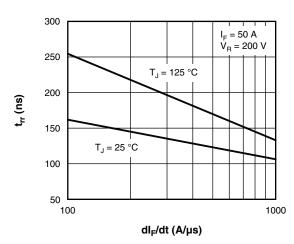


Fig. 7 - Typical Reverse Recovery Time vs. dl<sub>F</sub>/dt

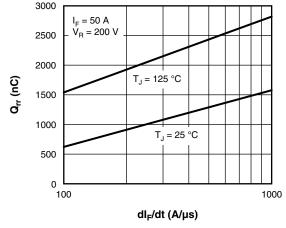


Fig. 8 - Typical Stored Charge vs. dl<sub>F</sub>/dt

#### Note

 $\begin{array}{l} \text{(1)} \ \ \text{Formula used: } T_C = T_J - (Pd + Pd_{REV}) \times R_{thJC}; \\ Pd = \text{Forward power loss} = I_{F(AV)} \times V_{FM} \text{ at } (I_{F(AV)}/D) \text{ (see fig. 5)}; \\ Pd_{REV} = \text{Inverse power loss} = V_{R1} \times I_R \text{ (1 - D); } I_R \text{ at } V_{R1} = \text{Rated } V_R \\ \end{array}$ 

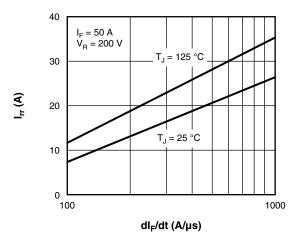


Fig. 9 - Typical Peak Recovery Current vs. dl<sub>F</sub>/dt

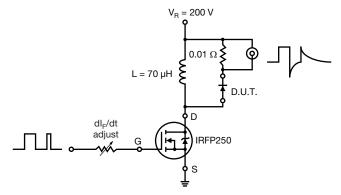
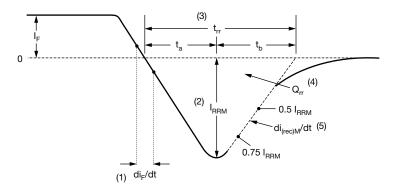


Fig. 10 - Reverse Recovery Parameter Test Circuit



- (1) di<sub>F</sub>/dt rate of change of current through zero crossing
- (2)  $I_{RRM}$  peak reverse recovery current
- (3)  $\rm t_{rr}$  reverse recovery time measured from zero crossing point of negative going  $\rm I_F$  to point where a line passing through 0.75  $\rm I_{RRM}$  and 0.50  $\rm I_{RRM}$  extrapolated to zero current.
- (4)  $\mathbf{Q}_{\rm rr}$  area under curve defined by  $\mathbf{t}_{\rm rr}$  and  $\mathbf{I}_{\rm RRM}$

$$Q_{rr} = \frac{t_{rr} x I_{RRM}}{2}$$

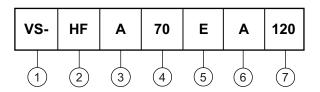
(5)  $di_{(rec)M}/dt$  - peak rate of change of current during  $t_b$  portion of  $t_{rr}$ 

Fig. 11 - Reverse Recovery Waveform and Definitions



#### **ORDERING INFORMATION TABLE**

**Device code** 



- 1 Vishay Semiconductors product
- 2 HEXFRED® family
- **3** Process designator (A = electron irradiated)
- Average current (70 = 70 A)
- 5 Circuit configuration (two separate diodes, antiparallel pin-out)
- 6 Package indicator (SOT-227 standard insulated base)
- 7 Voltage rating (120 = 1200 V)

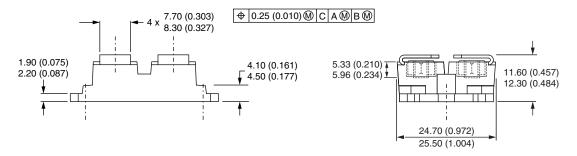
CIRCUIT CONFIGURATION					
CIRCUIT	CIRCUIT CONFIGURATION CODE	CIRCUIT DE	RAWING		
			Lead Assignment		
Two separate diodes, antiparallel pin-out	E	40 3	4		

LINKS TO RELATED DOCUMENTS				
Dimensions	www.vishay.com/doc?95423			
Part marking information	www.vishay.com/doc?95425			

## SOT-227 Generation 2

#### **DIMENSIONS** in millimeters (inches)





#### Note

· Controlling dimension: millimeter



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